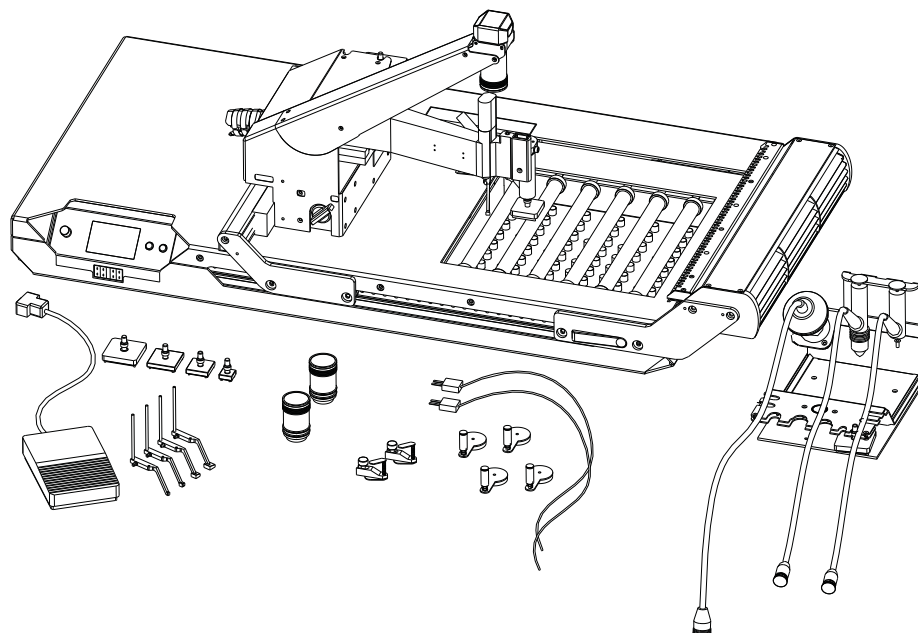


EXPERT 10.6-HV


Rework Station with 3000W hybrid under heater. The heating area of 275x245mm² is adjustable to PCB size. Automated SMD placement process by Auto Vision Placer (AVP) incl. Easy Solder software package and DBL 06 control unit with six high resolution sensors inputs for thermocouples (Type K).

This system is particularly suitable for mid size and big PCBs with Fine Pitch components with varying package dimensions.

Standard Equipment (Art.No. DB00.1065)




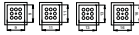
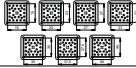
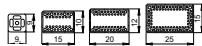




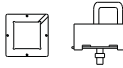



- Tool set for dispensing, placing, residual solder removal and soldering with magazine
- Set of placement nozzles (BGA/CSP) 3mm, 5mm, 8mm, 10mm
- Set of solder nozzles (BGA) 15mm, 27mm, 35mm, 40mm
- Two camera lenses (BGA und CSP)
- Two thermo couple sensors (type K)
- Four PCB magnet holder 40,5mm (standard)
- Two PCB clips to install at hand rest
- Foot switch
- Rework ABC and manual

Technical Data

System power consumption:	3500 VA
Power solder pen :	300 W, 35 l/min
Power underheater:	600 - 3000 W, 6 x IR lamps
Effective heating area:	275 x 245 mm ²
Recommended max. PCB size:	305 x 305 mm ²
Resolution motion system:	0,001 mm
Placement accuracy :	± 0,015 mm (Flip Chip)* ± 0,030 mm (CSP) ± 0,040 mm (BGA) ± 0,070 mm (Maxi BGA)*
High resolution CMOS-camera:	5 Mio. Pixel, USB2
Camera field of view (FOV):	18 x 14 mm ² (Flip Chip)* 37 x 28 mm ² (CSP) 50 x 37 mm ² (BGA) 85 x 65 mm ² (Maxi BGA)*
Mains:	1 Phase, 230VAC, 25A/Phase, Fuse 16A Connector Type CEE 32A (3 phase)
Pressurized air:	5 - 8 bar, 100l/min clean dry air
Foot print:	865 x 460 mm ²
*Optional Extras	

EXPERT 10.6-HV

Optional Extras

SF66.0004	Micro SMD nozzles and lens for AVP 4 licence MS, 3 n, 3 solder n, lens FC	<div>SF66.0022</div> <div></div>
DVSX.0007	Report with pcb identification for ES 05, licence RP	<div>DVSX.0007</div> <div><div></div><div>Report</div></div>
SF66.0110	Lens Maxi BGA for AVP4/4XL, f=16mm, 65*85mm	<div>SF66.0110</div> <div><div></div><div>Maxi-BGA AVP4</div></div>
LW40.1097	Soldering nozzle set CSP/QFN (lead free)* for all CSP types, 4 pieces (9, 11, 13, 16)	<div>LW40.1097</div> <div><div></div><div>(length + 1.4 mm)</div></div>
LW40.1099	Solder nozzle set BGA 7 for all (98%) types of BGA, 7 pieces	<div>LW40.1099</div> <div></div>
LW01.0400	Soldering tool set SO (lead free)* for all SO...SOL...TSOP, 4 pieces	<div>LW01.0400</div> <div><div></div><div>(length + 1.4 mm)</div></div>
LW01.0100	Soldering tool set QFP for all PLCC ...QFP, 7 pieces	<div>LW01.0100</div> <div></div>
SF36.1001	PCB flex support 40.5 for HIF 08 and IRF, "10 pin"	<div>SF36.1001</div> <div></div>
SF03.0014	PCB magnet holder Easy Lock 40.5 (snap) for IR/IRD/IRH/IRF radiation element	<div>SF03.0014</div> <div><div></div><div>40.5</div></div>
SF03.0019	PCB clamping holder 40.5 with 3 fingers for mobil phone pcbs on HB05/IR/IRD/IRH/IRF	<div>SF03.0019</div> <div><div></div><div>40.5</div></div>
LWxx.xxx4	Reballing oven and masks for all types of BGA/CSP, your choice	<div>LWxx.xxx4</div> <div></div>
SF71.0001	Side Camera for ES 05, camera, stand, cable, DVD	<div>SF71.0001</div> <div></div>
DB00.0025	Nitrogen input for DBL 04/05/06 (2.p.r) reduces consumption of N2 for vacuum	<div>DB00.0025</div> <div><div></div><div>N₂</div></div>
SF00.0028	Line connector CEE 32 A for HIF 08/09/10 / IRF 07 with hints	<div>SF00.0028</div> <div></div>